

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT6119243

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
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JONG-SUN KO	05/11/2020
YONG JAE KIM	05/11/2020
WON HEE LEE	05/11/2020
JIN WOO JUNG	05/11/2020
JEE RAK CHOI	05/11/2020
YOON SUNG KYUNG	05/11/2020
SEUNG HYUN KIM	05/11/2020
JI SU KIM	05/11/2020
JOONG HYUN PARK	05/11/2020
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PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16488365

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PATENT

ATTORNEY DOCKET NUMBER:	123252-5185
NAME OF SUBMITTER:	SANDRA JOHNSON
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DATE SIGNED:	05/22/2020
Total Attachments: 3 source=123252-5185_dec_1#page1.tif source=123252-5185_dec_1#page2.tif source=123252-5185_dec_1#page3.tif	

other relevant treaties;

I hereby authorize and request the United States Patent and Trademark Office and officials in patent offices in foreign countries to issue any and all of said Letters Patent to the ASSIGNEE as the assignee of my entire right, title, and interest in and to the same, for the sole use and benefit of the ASSIGNEE, and its lawful successors and assigns, to the full end of the term for which said Letters Patent may be granted;

I hereby grant the attorney of record the power to insert on this Assignment any further identification that may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office or other authority for recordation of this document;

I hereby covenant that I have the full right to convey the interest assigned by this Assignment, and I have not executed and will not execute any agreement in conflict with this Assignment; and

Further, I hereby further covenant and agree that I will, without further consideration, communicate with the ASSIGNEE, and its lawful successors and assigns, any facts known to me respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said ASSIGNEE, and its lawful successors or assigns, execute all divisional, continuation, continuation-in-part, and reissue applications, make all rightful oaths and generally do everything possible to aid the ASSIGNEE, and its lawful successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the ASSIGNEE, and its lawful successors and assigns.

IN TESTIMONY WHEREOF, I have hereunto set my hands.

NAME OF INVENTOR (Full Legal Name) : SONG, In Seong

Signature: SONG, In Seong Date: May 11, 2020

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Signature: KO, Jong-sun Date: May 11, 2020

NAME OF INVENTOR (Full Legal Name) : KIM, Yong Jae

Signature: Kim, Yong Jae Date: May 11, 2020

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Signature: LEE, Won Hee Date: May 11, 2020

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Signature: JUNG, Jin Woo Date: May 11, 2020

NAME OF INVENTOR (Full Legal Name) : CHOI, Jee Rak

Signature: Choi, Jee Rak Date: May 11, 2020

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BE SENT TO CLIENT\WCombined Declaration and

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